



JP1296167

Biblio

Page 1

PROBE CARD

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 Inventor(s): NAKAJIMA YASUHARU
 Applicant(s): MITSUBISHI ELECTRIC CORP
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Abstract

PURPOSE: To make the measurement of electric characteristic of a semiconductor element highly accurate, by mixing-in an electric wave absorbing material at least in a portion adjacent to a probe needle of a fixing member for fixing said probe needle so as to absorb the high frequency components.

CONSTITUTION: A circuit pattern 4 is formed on the surface of a substrate of a probe card 2. A probe needle 9 is fixed to a through hole 7 via a fixing member 8. Electric wave absorbing material composed of magnetic substance such as ferrite powders or the like is mixed in epoxy resin of the fixing member 8. An end 9a of the probe needle 9 is brought into touch with each pad 13 formed on a semiconductor wafer 12 on a probing device 11. Accordingly, when the electric characteristic of the semiconductor is measured, an oscillating phenomenon brought about by way of the parasitic capacity present between the needles 9 is absorbed by the wave absorbing material. Therefore, the measurement of the electric characteristic can be positively performed with high accuracy.

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